

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)	Attorney Docket No.: MIYOSH0006
)	
Kazuyoshi TENDOU et al.)	Confirmation No.: 5987
)	
Serial No.: 10/596,387)	Group Art Unit: 1796
)	
Filed: April 13, 2007)	Examiner: Michael J. FEELY
)	
For: EPOXY RESIN MOLDING)	Date: September 16, 2009
MATERIAL FOR SEALING AND)	
ELECTRONIC COMPONENT)	

AMENDMENT (B)

MAIL STOP: AMENDMENT
U.S. Patent and Trademark Office
Customer Service Window
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

In response to the non-final Office Action mailed June 22, 2009, please amend the application identified above as follows:

Amendments to the Claims are reflected in the listing of claims, which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.